

# ELECTRONICS DEVICES AND MATERIALS

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## FERROELECTRIC DEVICES

1. Capacitor ~high permittivity devices~
2. Piezoelectric Devices
3. Pyroelectric Devices
4. Ferroelectric Memory Devices
5. Electrooptic Devices

## VARIOUS EFFECTS IN MATERIALS

Input → **Material Device** → Output

Output \ Input	Charge Current	Magnetization	Strain	Temperature	Light
Electric Field	Permittivity Conductivity	Elect.-Mag. efficient	Converse piezo-effect	Elec. Caloric effect	Elec.-optic effect
Magnetic Field	Mgg.-elect. effect	Permeability	Magneto- striction	Mag.caloric effect	Mag.optic effect
Stress	Piezoelectric effect	Piezomag. effect	Elastic constant		Photoelastic effect
Heat	Pyroelectric effect		Thermal expansion	Specific heat	
Light	Photovoltaic effect		Photostriction		Refractive index

Sensor
Actuator

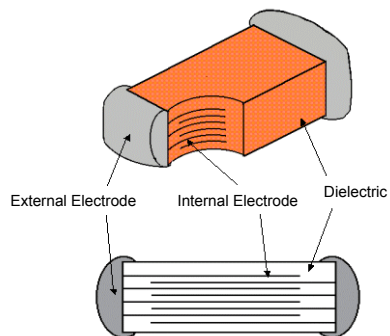
## CERAMIC CAPACITORS ~HIGH PERMITTIVITY DIELECTRICS~

The basic Specifications required for capacitors:

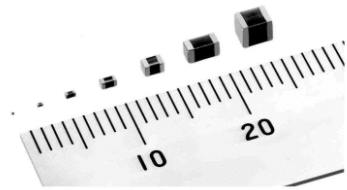
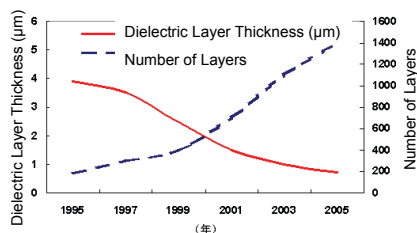
- **Small size, large capacitance**  
Materials with a large dielectric constant are desired.
- **High frequency characteristics**  
Ferroelectrics with a high dielectric constant are sometimes associated with dielectric dispersion, which must be taken into account for practical applications.
- **Temperature characteristics**  
We need to design materials to stabilize the temperature characteristics.

# MULTILAYER CERAMIC CAPACITOR (MLCC)

4-5



$$C = \epsilon_0 \epsilon_r \frac{A}{d} = n \epsilon_0 \epsilon_r \frac{S}{L/n}$$

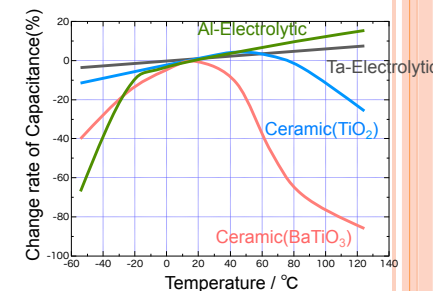


# TEMPERATURE CHARACTERISTICS

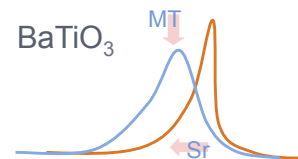
4-6

Categories of dielectrics

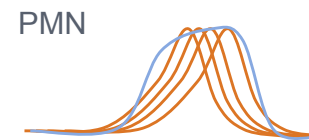
- thermal compensation type ( $TiO_2$ )  
high frequency, filtering, amplifier cir.
- high permittivity type ( $BaTiO_3$ )  
coupling or decoupling circuit



## Some approach to improve Temp. Characteristics



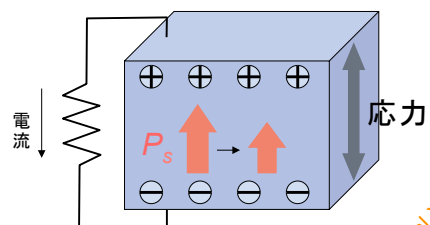
Shifter additive (decreaser: Sr, elevator: Pb)  
Depressor additive ( $MgTiO_3$ ,  $CaTiO_3$ )



Combination of ferroelectrics with different composition (different Curie Temp.)

# PIEZOELECTRIC DEVICES

4-7



Relationship of polarization and piezoelectric strain

$$P = \epsilon_0 \epsilon(x) E$$

Fundamental Piezoelectric equations:

$$x = c_{(E)} X + d E$$

$$P = d X + \epsilon_0 \epsilon(x) E$$

external  $E=0$   
 $P=dX$

$$E = \frac{P}{\epsilon_0 \epsilon(x)}$$

$$\frac{dX}{\epsilon_0 \epsilon(x)}$$

Therefore  $g = \frac{d}{\epsilon_0 \epsilon_r}$

## Piezoelectric Figures of Merit

**Piezoelectric Strain Constant: d**

$$x = d E$$

External electric field: E,  
magnitude of the induced strain : x

An important figure of merit for actuator applications

**Piezoelectric voltage constant: g**

$$E = g X$$

External stress: X,  
induced electric field: E

An important figure of merit for sensor applications

# OTHER IMPORTANT FIGURE OF MERIT FOR PIEZOELECTRIC APPLICATIONS

4-8

Electromechanical Coupling Factor: k

$$k^2 = \frac{\text{Stored mechanical energy}}{\text{Input electrical energy}}$$

Conversion rate between electrical energy and mechanical energy

Mechanical Quality :  $Q_m$

$$Q_m = \frac{\omega_0}{2\Delta\omega} \quad \omega_0: \text{resonance frequency}$$

The inverse of mechanical loss

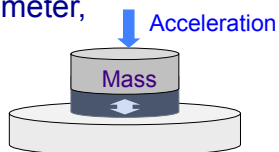
Acoustic Impedance : Z

Evaluating the acoustic energy transfer between two materials

## APPLICATIONS OF PIEZOELECTRICS

Gas igniter Pressure sensor, Accelerometer,

Stress → Internal electrical field



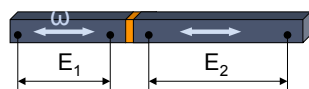
Basic structure of an accelerometer

Piezoelectric transformer

External electrical field

→ Stress

→ Internal electrical field

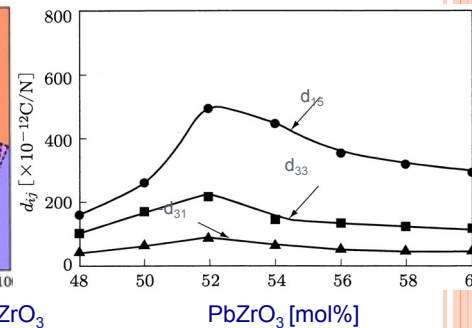
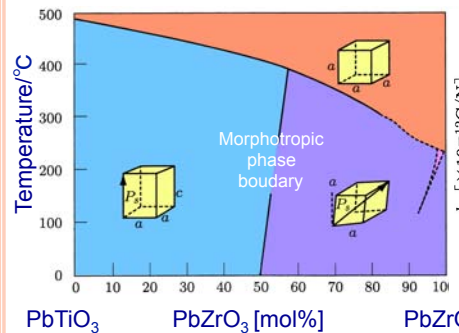


Basic structure of a piezoelectric transformer

Piezo-actuator • Ultrasonic Motor

External electrical field → Stress

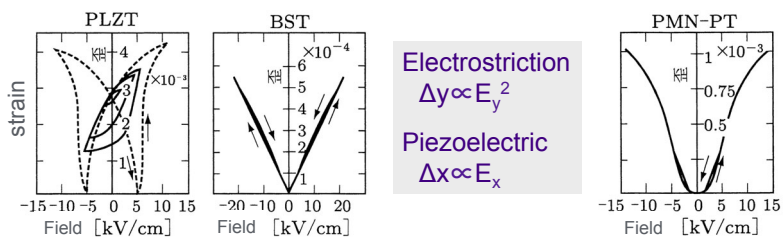
## PZT'S COMPOSITION AS PIEZOELECTRIC DEVICES



Dependence of several d constants on composition near morphotropic phase boundary in the PZT system

## CERAMIC ACTUATOR MATERIALS

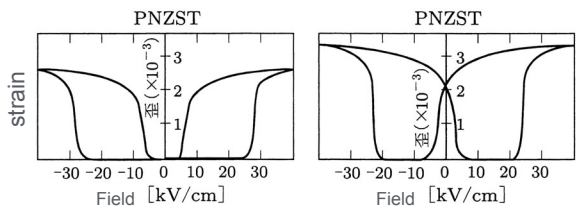
~PIEZOELECTRIC, ELECTROSTRICTIVE AND PHASE CHANGE MATERIAL~



Electrostriction  $\Delta y \propto E_y^2$   
Piezoelectric  $\Delta x \propto E_x$

Piezoelectric material,  
(Pb, La)(Zr, Ti)O<sub>3</sub>, Ba(Sn, Ti)O<sub>3</sub>

Electrostrictive material,  
Pb(Mg<sub>1/3</sub>Nb<sub>2/3</sub>, Ti)O<sub>3</sub>



Phase change material, Pb (Zr, Sn, Ti)O<sub>3</sub>

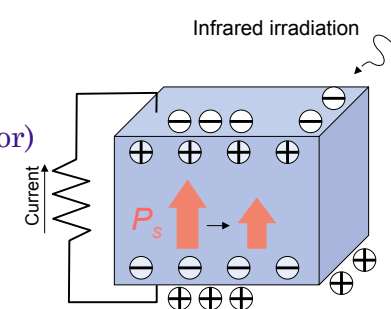
## PYROELECTRIC DEVICES

### Types of Infrared-sensors

- ◆ semiconductor type  
→ Imaging and its processing
- ◆ pyroelectric type (Pyrosensor)  
→ Infrared light sensors, Temperature sensors

### The merits of pyrosensors

- ◆ wide range of response frequency
- ◆ use at room temperature
- ◆ quick response in comparison with other temperature sensors
- ◆ low costs



Principle of pyroelectric sensor

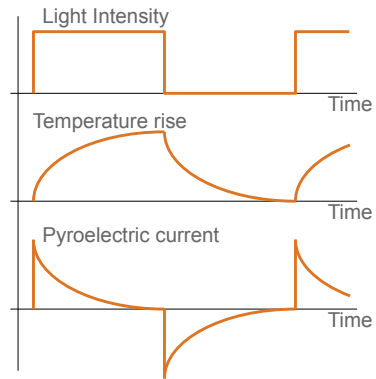
A temperature increase due to the infrared irradiations (such as human body)  
⇒ Spontaneous polarization decrease  
⇒ Variation in electric charge (or current)

## PYROELECTRIC RESPONSE

Current responsivity:  $r_i$

$$r_i = \frac{\eta \rho}{\rho C_p h}$$

$\eta$ : transmittance of incident radiation  
 $\rho$ : pyroelectric coefficient  
 $\rho$ : density of pyro-material  
 $C_p$ : specific heat of detector  
 $h$ : thickness of detector



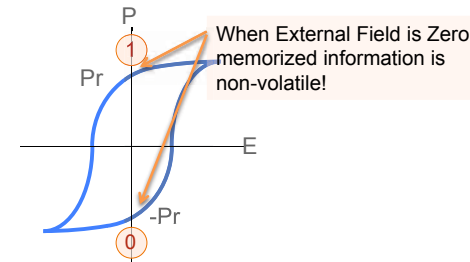
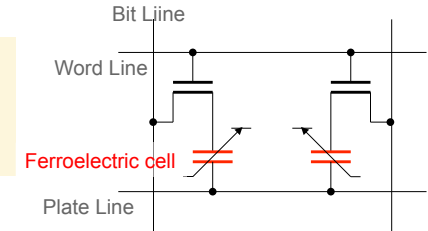
Pyroelectric response to chopped IR irradiation

Example of pyro-material for IR detector:

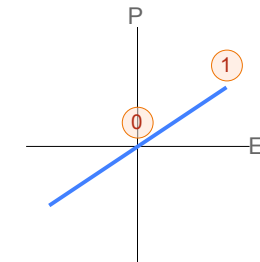


## FERROELECTRIC MEMORY DEVICES

FeRAM (FRAM)  
 Non-volatile memory device  
 (cf. MRAM, PRAM)



Ferroelectric for memory-cell (FeRAM)

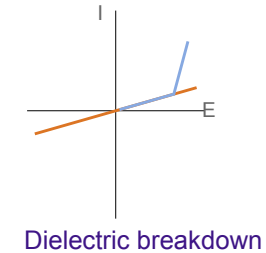
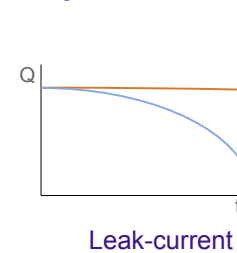
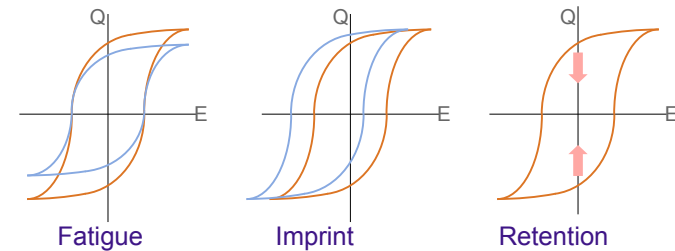


Paraelectrics for memory-cell (DRAM)

## EQUIVALENT CIRCUITS AND SCHEMATIC STRUCTURES OF TYPICAL MEMORY DEVICES

	DRAM	Flash EEPROM	FeRAM	MRAM	PRAM
Equivalent Circuit					
Memory State	1				
	0				

## PROBLEMS OF FERROELECTRICS FOR FERAM APPLICATIONS



## FERROELECTRIC MATERIALS FOR FERAM

PZT (Pb(Zr,Ti)O <sub>3</sub> )	Material	SBT (SrBi <sub>2</sub> Ta <sub>2</sub> O <sub>9</sub> )
Large Pr Relatively easy fabrication	<b>Merits</b>	Low Ec (low operation Voltage) Good tolerance for <b>Fatigue</b>
Relatively large Ec Large Fatigue Preparation conditions (Pb-composition)	<b>Demerits</b>	Low Pr Difficult preparation conditions (High Temp., Bi-composion)
La addition → leakage & Ec Ca, Sr additions → Imprint and Retention Oxide Electrode, Buffer → Fatigue Properties Film Orientation → Pr, Fatigue, reduction of thickness	<b>Improvement Approach</b>	Nb addition → Increment of Pr SBT-BT composite → dielectric properties
Ramtron, Fujitsu, ...		Symetrix, Panasonic, NEC, ...

## ELECTROOPTIC DEVICES



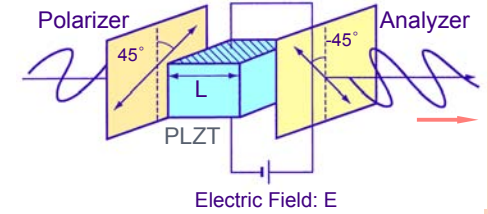
Birefringence

Second-order electrooptic effect (Kerr effect)

Birefringence:  $\Delta n$

$$\Delta n = -\frac{1}{2} R n^3 E^2$$

R: quadratic electrooptic coefficient  
n: original refractive index (E=0)  
E: electric field



Fundamental Construction of an electrooptic light shutter

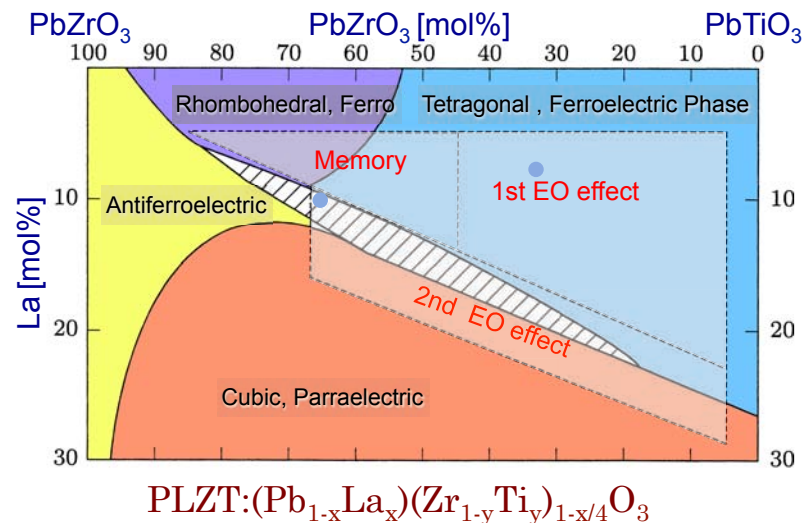
⇔ First-order electrooptic effect (Pockels effect)

### Typical Application of Electrooptic Devices

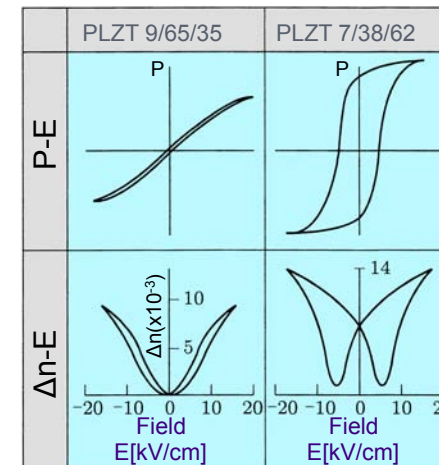
Light Shutter, Light Switch, Waveguide Modulator

- high speed, high contrast, gradation
- × high cost, high operation voltage

## RELATION BETWEEN PLZT COMPOSITION AND STRUCTURE AND ELECTROOPTIC APPLICATION



## POLARIZATION AND BIREFRINGENCE AS A FUNCTION OF ELECTRIC FIELD FOR PLZT



2nd order EO effect    1st order EO effect

Polarization P and Birefringence  $\Delta n$  as a Function of Electric Field E for some PLZT ceramics

## DIELECTRIC MATERIALS OF ELECTROOPTIC DEVICES

4-21

Pockels (1st) and Kerr (2nd) electrooptic coefficients for various materials

	Material	$r (\times 10^{-10} [\text{m/V}])$
Primary electrooptic coefficient	LiNbO <sub>3</sub>	0.17
	Ba <sub>2</sub> (K <sub>0.9</sub> Na <sub>0.1</sub> )Nb <sub>5</sub> O <sub>15</sub>	0.52
	KH <sub>2</sub> PO <sub>4</sub>	0.52
	(Sr <sub>0.5</sub> Ba <sub>0.5</sub> )Nb <sub>2</sub> O <sub>6</sub>	2.10
	PLZT (8/65/35) (GS = 10 [ $\mu\text{m}$ ])	5.23
	PLZT (8/65/35) (GS = 3 [ $\mu\text{m}$ ])	6.12
		$R (\times 10^{-16} [\text{m}^2/\text{V}^2])$
Secondary electrooptic coefficient	KTa <sub>0.65</sub> Nb <sub>0.35</sub> O <sub>3</sub>	5.30
	PLZT (9/65/35) (GS = 2 [ $\mu\text{m}$ ])	9.12
	PLZT (10/65/35) (GS = 2 [ $\mu\text{m}$ ])	1.07

## REQUIRED PROPERTIES FOR ELECTROOPTIC DEVICES

4-22

Required Properties for electrooptic devices

- ◆ high electrooptic coefficient
- ◆ good mechanical properties (especially high toughness)
- ◆ high transmittance
- ◆  $\Delta n$  close to zero, when external electric field is zero
- ◆ low porosity, high sintered density

